

PRODUCT SPECIFICATION

MONO LCD MODULE MODEL: G1206C1WVW6B-F0 Ver:1.0

< >> Preliminary Specification

< >> Finally Specification

CUSTOMER'S APPROVAL					
CUSTOMER:					
SIG	NATURE:	DATE:			
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APPROVED	PM	PD	PREPARED
ВҮ	REVIEWED	REVIEWED	ву
2018/125	软件	4.19-	潘远良

Revision Status

Version	Revise Date	Page	Content	Modified By
Ver. 1.0	2018.01.23		First Issued	

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1. Features

The features of LCD are as follows

* Display mode : DFSTN/Transmissive/ Negative

* Drive IC : Uci6963C * Interface Input Data : 8080 Series

* Driving Method : 1/64Duty, 1/9 Bias

* Viewing Direction : 6 O'clock

* Backlight :LED/ Side White

*Sample NO. : G1206C1WVW6B-F0_01/20180116

2. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Module Size	78.0 (W) x 70.0 (H) x 14.0 MAX(D)	mm
Number of Dots	128 x 64	Dots
View Display Area	62.0 (W) x 44.0 (H)	mm
Activity Display Area	56.28 (W) x 38.36 (H)	mm
Dot Size	0.4(W) x 0.56(H)	mm
Dot Pitch	0.44 (W) x 0.6 (H)	mm

3. ELECTRICAL SPECIFICATIONS

3-1 ABSOLUTR MAZIMUM RATINGS (Ta = 25 °C)

Item	Symbol	Star			
item	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	VDD-VSS	-0.3	-	7.0	V
Supply Voltage For LCD Drive	V _{op} = V _{DD} - V ₀	-0.3	-	13	V
Operating Temp.	Тор	-20	-	+70	°C
Storage Temp.	Tst	-30	-	+80	°C

^{*.} NOTE: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

3-2 ELECTRICAL CHARACTERISTICS

Item	Item		Item Symbol Test Min.		Тур.	Max.	Unit
Logic supply	Voltage	VDD — Vss		4.5	5	5.5	V
LCD Dri	ive	VDD -V _{EE}	Ta = 25 °C	12.8	13	13.2	V
Input Voltage	"H" Level	V _{IH}	VDD=5V ± 10%	VDD-2.2	1	Vdd	V
	"L" Level	V _{IL}		0	1	0.8	V
Frame Freq	luency	f_{FLM}		-	60	-	Hz
Current Cons	umption	I _{DD}		-	2.2	-	mA

3-3. BACKLIGHT

3-3-1. Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward current	IF		-	-	80	mΑ
Reverse Voltage	VR	Ta = 25 °C If=60mA		-	5	V
Power Dissipation	PD			-	198	mW

3-3-2. Electrical-optical Characteristics

Item	Symbol	Condition	М	in.	Ту	η.	Ma	ax.	Unit
Forward Voltage	VF		2	.9	3	.1	3	.3	V
Average Luminous Intensity	Lv	Lv If=60mA		200		300			cd/m ²
Colour coordinate	_	Ta = 25 °C	Χ	Υ	Χ	Υ	Χ	Υ	nm
Colour coordinate			0.25	0.25	0.28	0.28	0.32	0.32	11111
Lifetime			200	000		-		-	Hours

The brightness is measured without LCD panel

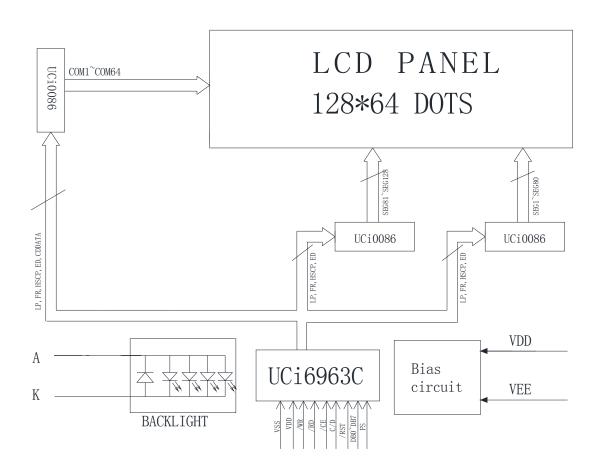
Backlight lifetime means luminance value larger than half of the original after 20000 hours' continuous working.

4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

4-1. INTERFACE PIN FUNCTION DESCRIPTION

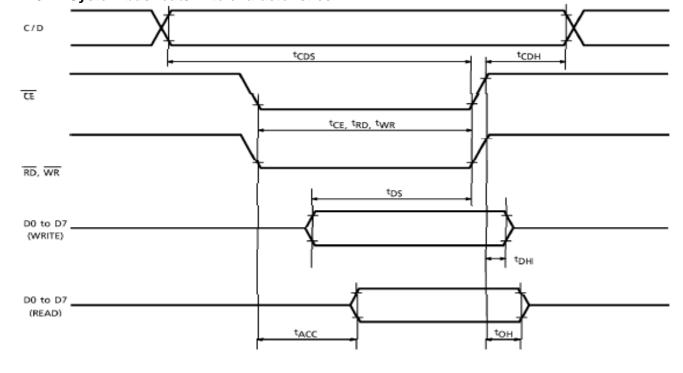
PIN NO.	SYMBOL	FUNCIONS			
1	FG	Frame ground			
2	Vss	Ground (0V)			
3	VDD	Supply voltage for logical circuit(5V)			
4	VEE	Supply voltage for LCD driving			
5	/WR	Write enable signal			
6	/RD	Read enable signal			
7	/CE	Chip selection signal			
8	C/D	Select the command is instruction or data			
9	/RET	Reset signal			
10-17	DB0~DB7	Data bus line			
18	FS	Font selection pin			
19	LEDA	Backlight (+5.0V)			
20	LEDK	Backlight (0V)			

4-2. BLOCK DIAGRAM



5. TIMING CHARACTERISTICS

5 - 1 System bus read/write characteristics



TEST CONDITIONS (Unless otherwise noted, $V_{DD} = 5.0V \pm 10\%$, $V_{SS} = 0V$, $T_{a} = -20$ to 75° C)

ITEM	SYMBOL	TEST CONDITIONS	MIN	MAX	UNIT
C/D Set-up Time	t _{CDS}	_	100	_	ns
C/D Hold Time	t _{CDH}	_	10	_	ns
CE, RD, WR Pulse Width	t _{CE} , t _{RD} , t _{WR}	_	80	_	ns
Data Set-up Time	t _{DS}	_	80	_	ns
Data Hold Time	^t DH	-	40	_	ns
Access Time	^t ACC	_	_	150	ns
Output Hold Time	tОН		10	50	ns

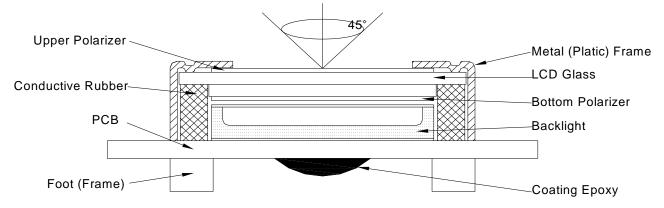
6. COMMAND LIST

COMMAND	CODE	D1	D2	FUNCTION
	00100001	X address	Y address	Set Cursor Pointer
REGISTERS SETTING	00100010	Data	00H	Set Offset Register
	00100100	Low address	High address	Set Address Pointer
	01000000	Low address	High address	Set Text Home Address
CET CONTROL WORD	01000001	Columns	00H	Set Text Area
SET CONTROL WORD	01000010	Low address	High address	Set Graphic Home Address
	01000011	Columns	00H	Set Graphic Area
	1000X000	_	_	OR mode
	1000X001	_	_	EXOR mode
	1000X011	_	_	AND mode
MODE SET	1000X100	_	_	Text Attribute mode
	10000XXX	_	_	Internal CG ROM mode
	10001XXX	_	_	External CG RAM mode
	10010000	_	_	Display off
	1001XX10	_	_	Cursor on, blink off
DICEL AV MODE	1001XX11	_	_	Cursor on, blink on
DISPLAY MODE	100101XX	_	_	Text on, graphic off
	100110XX	_	_	Text off, graphic on
	100111XX	_	_	Text on, graphic on
	10100000	_	_	1-line cursor
	10100001	_	_	2-line cursor
	10100010	_	_	3-line cursor
CURSOR PATTERN	10100011	_	_	4-line cursor
SELECT	10100100	_	_	5-line cursor
	10100101	_	_	6-line cursor
	10100110	_	_	7-line cursor
	10100111	_	_	8-line cursor
DATA AUTO DEAD /	10110000	_	_	Set Data Auto Write
DATA AUTO READ/ WRITE	10110001	_	_	Set Data Auto Read
VVKITE	10110010	_	_	Auto Reset
	11000000	Data	_	Data Write and Increment ADP
	11000001	l –	_	Data Read and Increment ADP
DATA DEAD (MIDITE	11000010	Data	_	Data Write and Decrement ADP
DATA READ/WRITE	11000011	l –	_	Data Read and Decrement ADP
	11000100	Data	_	Data Write and Nonvariable ADP
	11000101	_	_	Data Read and Nonvariable ADP
SCREEN PEEK	11100000	_	_	Screen Peek
SCREEN COPY	11101000			Screen Copy

7. QUALITY SPECIFICATIONS

7 - 1. LCM Appearance and Electric inspection Condition

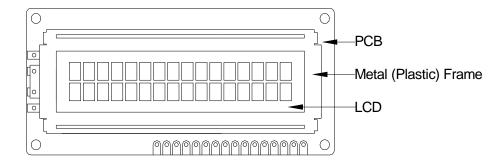
1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



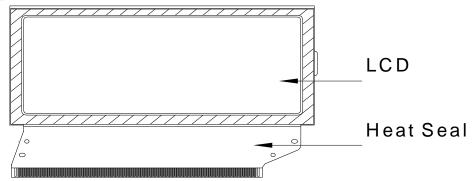
2. View Angle: with in 45° around perpendicular line.

7-2. Definition

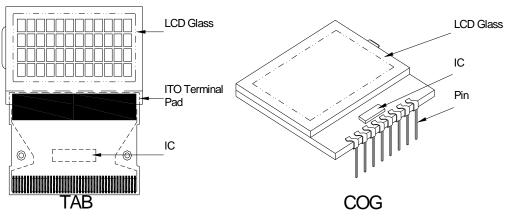
1. COB



2. Heat Seal



3.TAB and COG



7-3. Sampling Plan and Acceptance

1.Sampling Plan

MIL - STD - 105E (||) ordinary single inspection is used.

2.Acceptance

Major defect: AQL = 0.25%Minor defect: AQL = 0.65%

7-4. Criteria

1.COB

Defect	Inspection Item	Inspection Standards	
Major	PCB copper flakes peeling off	g off Any copper flake in viewing Area should be greater than 1.0mm ²	
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject
Major	PCB cutting defect	Exceed the dimension of drawing	Reject

2.SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing, extra, wrong component or wrong orientation		Reject
Minor	Component position shift component soldering pad	X < 3/4Z Y > 1/3D	Reject Reject
Minor	Component tilt component soldering pad	Y > 1/3D	Reject
Minor	Insufficient solder component PAD PCB	<i>θ</i> ≤ 20°	Reject

3. Metal (Plastic) Frame

Defect	Inspection Item	Inspection Standards					
Major	Crack / breakage	Any	Reject				
	W		L	Acceptable of Scratch			
		w<0.1mm	Any	Ignore			
		0.1 <u><</u> w<0.2mm	L <u><</u> 5.0mm	2			
Minor	Frame Scratch	0.2 <u><</u> w<0.3mm	L <u><</u> 3.0mm	1			
		w <u>></u> 0.3mm	Any	0			
		Note: 1. Above criteria applicable to scratch lines with distance greater than 5mm. 2. Scratch on the back side of frame (not visible) can be ignored.					
				Acceptable of Dents / Pricks			
		Φ<	2				
	Frame Dent , Prick	1.0<⊕ <u><</u> 1.5mm		1			
Minor	$\Phi = \frac{L + W}{2}$	1.51	0				
	2	Note: 1. Above criteria applicable to any two dent / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (no visible) can be ignored					
Minor	Frame Deformation	Exceed the dimension of drawing					
Minor	Metal Frame Oxidation	Any rust					

4. Flexible Film Connector (FFC)

Defect	Inspection Item	Inspection Standards					
Minor	Tilted soldering Within the angle +5°		Acceptable				
Minor	Uneven solder joint /bump		Reject				
		Expose the conductive line	Reject				
Minor	Hole $\Phi = \frac{L + W}{2}$	Ф > 1.0mm	Reject				
Minor	Position shift Y T T T T T T T T T T T T	Y > 1/3D	Reject				
WIITOT		X > 1/2Z	Reject				

5. Screw

Defect	Inspection Item	Inspection Standards		
Major	Screw missing/loosen		Reject	
Minor	Screw oxidation	Any rust	Reject	
Minor	Screw deformation	Difficult to accept screw driver	Reject	

6. Heatseal 、TCP 、FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	⊕> 0.5mm	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift Y D X	Y > 1/3D	Reject
IVIIIIOI		X > 1/2Z	Reject
Major	Conductive line break		Reject

7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards				
		Acceptable number of units				
	LED dirty, prick	Φ <u><</u> 0.10mm	Ignore			
		0.10<⊕ <u><</u> 0.15mm	2			
Minor		0.15<⊕ <u><</u> 0.2mm	1			
		Φ>0.2mm	0			
		The distance between any two spots should be > Any spot/dot/void outside of viewing area is accept				
Minor	Protective film tilt	Not fully cover LCD	Reject			
Major	COG coating	Not fully cover ITO circuit	Reject			

8. Electric Inspection

Defect	Inspection Item	Inspection Standards				
Major	Short		Reject			
Major	Open		Reject			

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9. Inspection Specification of LCD										
Defect	ect Inspect Item			Inspection Standards						
		* Glass Scratch	W			0.03	0.0	 		V>0.05
Minor	Linear Defect	* Polarizer Scratch	ACC.	L<5			L<3		Any	
	Linear Defect	* Fiber and Linear	NO.		,	1		1		Reject
		material	Note	L is th	e ler	ngth and \	N is th	e width of	the de	efect
		* Foreign material		Φ <u><</u>		0.1<⊕ <u><</u>	0.15	0.15<⊕ <u><</u> 0	.2	⊕>0.2
	Black Spot and	between glass and polarizer or glass	NO.	3E/ 100n	A / nm²	2		1		0
Minor	Polarizer Pricked	and glass * Polarizer hole or protuberance by external force	Note	Φ is t	he a	-		r of the de ects > 10n		
		* Unobvious			Φ<	0.3	0.3	<⊕ <u><</u> 0.5	0.	5 <⊕
	White Spot	transparant foreign material between	ACC.	3E/	4 / 10	00mm ²		1		0
Minor	and Bubble in polarizer	glass and glass or glass and polarizer * Air protuberance between polarizer and glass	Note	Φ is the average diameter Distance between two de						
	Segment Defect		Φ	Φ <u><</u> 0	.10	0 0.10<Φ <u><</u> 0		0.20<⊕	<u><</u> 0.25	⊕>0.25
		W - W - 1		3E <i>A</i> 100m	\ / nm²	2		1		0
Minor				W is more than 1/2 segment width					Reject	
		W	Note	$\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm						
			Φ	Φ <u><</u> 0	.10	0.10<⊕ <u><</u> 0.20				⊕>0.25
N 4'	Protuberant Segment $\Phi = (L + W)/2$		W	Glu	ie	W <u><</u> 1/2 Seg W <u><</u> 0.2		W <u><</u> 1/2 W <u><</u> 0		Ignore
Minor			ACC. NO.	3E <i>A</i> 100m		2		1		0
			1. Seg	1. Segment						
			Е	B <u><</u> (<u><</u> 0.4mm 0.∠		0.4 <b<u><1.0mm B>1</b<u>		1.0mm
	Assembly	Assembly Mis-alignment		·A	B-	-A<1/2B		A<0.2	B-A	N<0.25
Minor				dge Acceptable			Acc	Acceptable Acceptab		eptable
				2. Dot Matrix					1	
			Deformation>2°				Reject			
Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the above items: "Black spot" and "White Spot"							

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8. RELIABILITY

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70°C, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity	60°C, 90%RH, 96Hrs	2	GB/T2423.3 -2006
4	High Temperature Storage	80°C, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test	-20°C, 60min~70°C, 60min, 20 cycles.	2	GB/T2423.2 2 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X,Y,Z 30 min for each direction.	2	GB/T5170.1 4 -2009
8	Electrical Static Discharge	Air: ± 8 KV 150pF/330 Ω 5 times	2	GB/T17626.
	Electrical Static Discharge	Contact: ± 4 KV 150pF/330 Ω 5 times		-2006
9	Drop Test Height:80 cm,1 corner, 3 edges, 6 surfaces.		2	GB/T2423.8 -1995

Note: 1) Above conditions are suitable for our company standard products.

2) For restrict products, the test conditions listed as above must be revised.

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9. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichloro trifloro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent:

- Water
- Ketone
- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

(4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.

(5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is reequired.

(6) Storage

In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)

(7) Safety

- It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol.

Which should be burned up later.

When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

16/17 **Model No.:** EG1206C1FVW6B-A1 **Ver:1.0**

Issued Date: 2010.11.01 Doc. No.: 10. OUTLINE DIMENSION NOTE: The dimension with "()" is reference \overline{C} Q APPROVED LEDK DB0 9 DOTS SIZE SCALE 10:1 LEDA **RST** C/D S ∞ ∞ 99.0-REVISION RECORD 087 First 14. 0MAX III WAN DB6 'RD BACK пП REV /WR 085 15 2 DB4 VEE # 7 FRONT DB3 MDD 13 -2.50 -02.50 **DB2** VSS 20-01.00 \bigcirc DB1 FG CONNECTION CONNECTION VIEWING DIRECTION M PIN P2. 54*19=48. 26 -74. 4±0.3---78. 00---(56. 28 (A. A)) ₩ 8.00 ₩ (38.36 (A.A)) 44.00 (V. A) ± 0.2 58. 1 ± 0.3 65.00±0.3 -00.07 A В $\overline{\circ}$ Q

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